

QS5U17

Silicon N-channel MOSFET
Schottky Barrier DIODE

- 1) The QS5U17 combines Nch MOSFET with a Schottky barrier diode in a single TSMT5 package.
- 2) Low on-state resistance with fast switching.
- 3) Low voltage drive (2.5V).
- 4) The Independently connected Schottky barrier diode has low forward voltage.

Load switch, DC / DC conversion

Type	Package	Taping
	Code	TR
	Basic ordering unit (pieces)	3000
QS5U17		○

The drawing shows the mechanical specifications for a TSMT package. The top view includes dimensions for the overall width (2.9), the distance between the center of the leads (1.9), and the width of the leads (0.95). The side view shows the maximum height (1.0 MAX), the height of the leads (0.85), the thickness of the package (0.7), the height of the leads from the base (0.1), the thickness of the package (0.3), and the distance between the center of the leads (0.16). The package is labeled with (1) through (5) to indicate the locations of the leads.

The diagram shows a MOSFET with an ESD protection diode and a body diode. The MOSFET has a Gate terminal (1), a Source terminal (2), and a Drain terminal (3). An ESD protection diode (*1) is connected between the Gate and Source terminals. A body diode (*2) is connected between the Drain and Source terminals. The Drain terminal is also connected to a Cathode terminal (4) and a Drain terminal (5).

(1) Gate
(2) Source
(3) Anode
(4) Cathode
(5) Drain

*1 ESD PROTECTION DIODE
*2 BODY DIODE

Transistors

●Absolute maximum ratings (Ta=25°C)

<MOSFET>

Parameter		Symbol	Limits	Unit
Drain-source voltage		V_{DS}	30	V
Gate-source voltage		V_{GS}	12	V
Drain current	Continuous	I_D	±2.0	A
	Pulsed	I_{DP} *1	±8.0	A
Source current (Body diode)	Continuous	I_S	0.8	A
	Pulsed	I_{SP} *1	3.2	A
Channel temperature		T_{ch}	150	°C
Power dissipation		P_D *3	0.9	W/ELEMENT

<Di>

Repetitive peak reverse voltage	V_{RM}	25	V
Reverse voltage	V_R	20	V
Forward current	I_F	1.0	A
Forward current surge peak	I_{FSM} *2	3.0	A
Junction temperature	T_j	150	°C
Power dissipation	P_D *3	0.7	W/ELEMENT

<MOSFET AND Di>

Total power dissipation	P_D *3	1.25	W / TOTAL
Range of Storage temperature	T_{stg}	-55 to +150	°C

*1 $P_w \leq 10 \mu s$, Duty cycle $\leq 1\%$ *2 60Hz-1cyc. *3 Mounted on a ceramic board

●Electrical characteristics (Ta=25°C)

<MOSFET>

Parameter	Symbol	Min.	Typ.	Max.	Unit	Conditions
Gate-source leakage	I_{GSS}	—	—	10	μA	$V_{GS}=12V / V_{DS}=0V$
Drain-source breakdown voltage	$V_{(BR) DSS}$	30	—	—	V	$I_D=1mA, / V_{GS}=0V$
Zero gate voltage drain current	I_{DSS}	—	—	1	μA	$V_{DS}=30V / V_{GS}=0V$
Gate threshold voltage	$V_{GS(th)}$	0.5	—	1.5	V	$V_{DS}=10V / I_D=1mA$
Static drain-source on-state resistance	$R_{DS(on)}$ *	—	71	100	m Ω	$I_D=2.0A, V_{GS}=4.5V$
		—	76	107	m Ω	$I_D=2.0A, V_{GS}=4V$
		—	110	154	m Ω	$I_D=2.0A, V_{GS}=2.5V$
Forward transfer admittance	$ Y_{fs} $ *	1.5	—	—	S	$V_{DS}=10V, I_D=2.0A$
Input capacitance	C_{iss}	—	175	—	pF	$V_{DS}=10V$
Output capacitance	C_{oss}	—	50	—	pF	$V_{GS}=0V$
Reverse transfer capacitance	C_{rss}	—	25	—	pF	$f=1MHz$
Turn-on delay time	$t_{d(on)}$ *	—	8	—	ns	$I_D=1.0A$
Rise time	t_r *	—	10	—	ns	$V_{DD} \doteq 15V$
Turn-off delay time	$t_{d(off)}$ *	—	21	—	ns	$V_{GS}=4.5V$
Fall time	t_f *	—	8	—	ns	$R_L=15\Omega$
Total gate charge	Q_g *	—	2.8	3.9	nC	$V_{DD} \doteq 15V$
Gate-source charge	Q_{gs} *	—	0.6	—	nC	$V_{GS}=4.5V$
Gate-drain charge	Q_{gd} *	—	0.8	—	nC	$I_D=2.0A$

*Pulsed

<Body diode (source-drain)>

Forward voltage	V_{SD} *	—	—	1.2	V	$I_S=3.2A / V_{GS}=0V$
-----------------	------------	---	---	-----	---	------------------------

* Pulsed

<Di>

Forward voltage	V_F	—	—	0.45	V	$I_F=1.0A$
Reverse current	I_R	—	—	200	μA	$V_R=20V$

Transistors

●Electrical characteristic curves

<MOSFET>

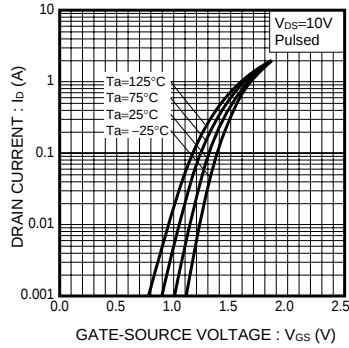


Fig.1 Typical Transfer Characteristics

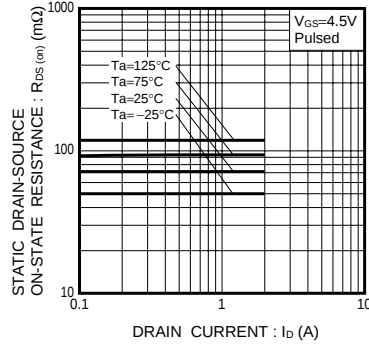


Fig.2 Static Drain-Source On-State Resistance vs. Drain Current

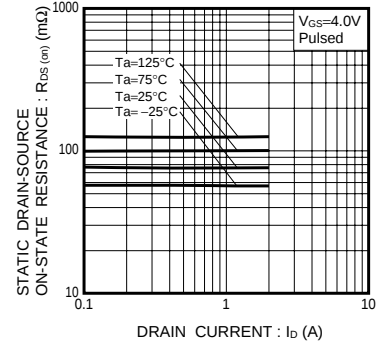


Fig.3 Static Drain-Source On-State Resistance vs. Drain Current

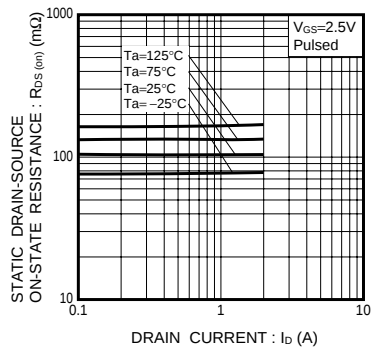


Fig.4 Static Drain-Source On-State Resistance vs. Drain Current

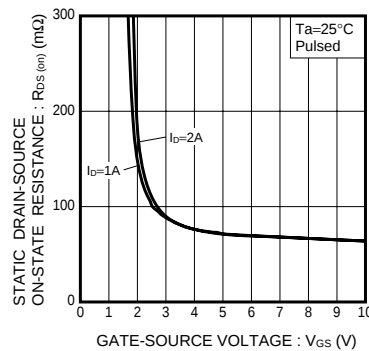


Fig.5 Static Drain-Source On-State Resistance vs. Gate-Source Voltage

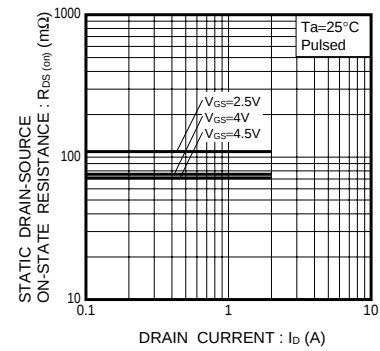


Fig.6 Static Drain-Source On-State Resistance vs. Drain Current

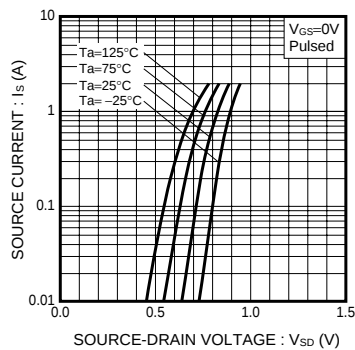


Fig.7 Reverse Drain Current vs. Source-Drain Current

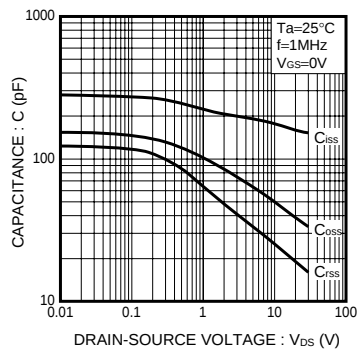


Fig.8 Typical Capacitance vs. Drain-Source Voltage

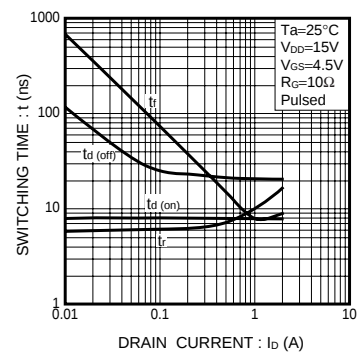


Fig.9 Switching Characteristics

Transistors

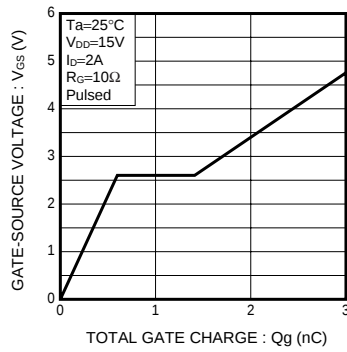


Fig.10 Dynamic Input Characteristics

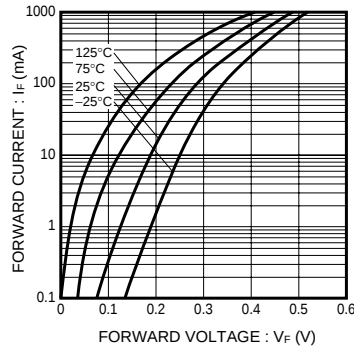


Fig.11 Forward Current vs. Forward Voltage

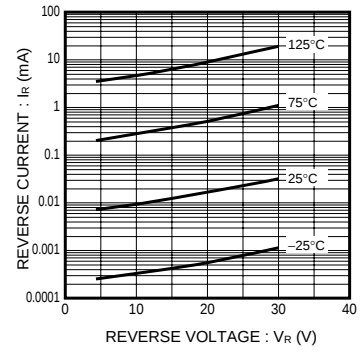


Fig.12 Reverse Current vs. Reverse Voltage

●Measurement circuits

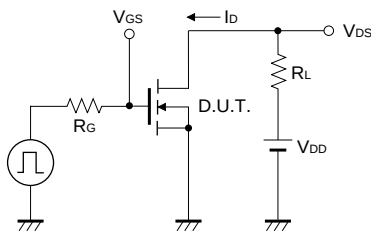


Fig.13 Switching Time Measurement Circuit

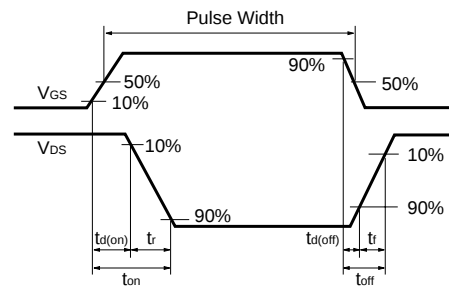


Fig.14 Switching Waveforms

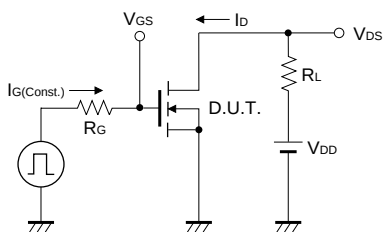


Fig.15 Gate Charge Measurement Circuit

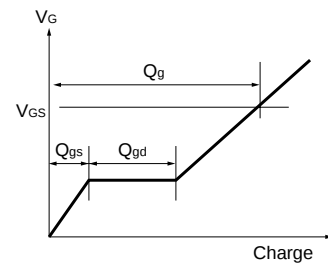


Fig.16 Gate Charge Waveform

Notes

- No technical content pages of this document may be reproduced in any form or transmitted by any means without prior permission of ROHM CO.,LTD.
- The contents described herein are subject to change without notice. The specifications for the product described in this document are for reference only. Upon actual use, therefore, please request that specifications to be separately delivered.
- Application circuit diagrams and circuit constants contained herein are shown as examples of standard use and operation. Please pay careful attention to the peripheral conditions when designing circuits and deciding upon circuit constants in the set.
- Any data, including, but not limited to application circuit diagrams information, described herein are intended only as illustrations of such devices and not as the specifications for such devices. ROHM CO.,LTD. disclaims any warranty that any use of such devices shall be free from infringement of any third party's intellectual property rights or other proprietary rights, and further, assumes no liability of whatsoever nature in the event of any such infringement, or arising from or connected with or related to the use of such devices.
- Upon the sale of any such devices, other than for buyer's right to use such devices itself, resell or otherwise dispose of the same, no express or implied right or license to practice or commercially exploit any intellectual property rights or other proprietary rights owned or controlled by
- ROHM CO., LTD. is granted to any such buyer.
- Products listed in this document are no antiradiation design.

The products listed in this document are designed to be used with ordinary electronic equipment or devices (such as audio visual equipment, office-automation equipment, communications devices, electrical appliances and electronic toys).

Should you intend to use these products with equipment or devices which require an extremely high level of reliability and the malfunction of which would directly endanger human life (such as medical instruments, transportation equipment, aerospace machinery, nuclear-reactor controllers, fuel controllers and other safety devices), please be sure to consult with our sales representative in advance.

About Export Control Order in Japan

Products described herein are the objects of controlled goods in Annex 1 (Item 16) of Export Trade Control Order in Japan.

In case of export from Japan, please confirm if it applies to "objective" criteria or an "informed" (by MITI clause) on the basis of "catch all controls for Non-Proliferation of Weapons of Mass Destruction.